

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	6	("3688159" "4866503").PN. de-10022341-\$.did. ch-445628-\$. did. gb-1155236-\$.did. gb-1168851-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:30
S2	2	"US 20060175630"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2007/06/25 09:50
S3	3	"20040120096"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:30
S4	2	"20040120096".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:30
S5	18	("4853762" "4965658" "5168425" "5489802" "6297549" "6303974"). PN. ("5798566" "6122170" "6864574"). PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:55
S6	5	S5 and (rubber elastic\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 15:47
S7	336972	(semiconductor ic chip die (integrated near circuit\$2)) and (rubber elastic\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 15:50

EAST Search History

S8	34199	(semiconductor ic chip die (integrated near circuit\$2)) and ((rubber elastic\$4) with seal\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 15:51
S9	228664	(heat near (sink radiat\$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 15:52
S10	1888	S8 and S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 15:53
S11	1343	S10 and power	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 15:53
S12	203	S11 and (encapsulat\$3 encapsulant)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 18:35
S13	2859902	rubber elastin elastic\$4 resilien\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 18:38
S14	4130155	semiconductor ic die dice (integrated near circuit\$2) chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 18:49

EAST Search History

S15	2533263	cool\$3 (heat near (radiat\$3 sink spreader))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 18:50
S16	300396	encapsulat\$3 encapsulant	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 18:52
S17	13733	S13 and S14 and S15 and S16	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 19:30
S18	3515	S17 and motor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 19:41
S19	232	S18 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 19:42
S20	1	S18 and "257"/181.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 19:42
S21	2859902	rubber elastin elastic\$4 resilien\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 20:58

EAST Search History

S22	4130155	semiconductor ic die dice (integrated near circuit\$2) chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 20:58
S23	2533263	cool\$3 (heat near (radiat\$3 sink spreader))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 20:58
S24	300396	encapsulat\$3 encapsulant	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 20:58
S25	13733	S21 and S22 and S23 and S24	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 21:00
S26	3	S25 and 257/181.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 21:00
S27	121110	S21 and S22 and S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 21:00
S28	25	S27 and 257/181.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 21:34

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S29	191978	S21 same S22	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 21:35
S30	259442	S22 same S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 21:36
S31	23872	S29 and S30	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 21:36
S32	3755	S31 and ("257"/\$.ccls. "438"/\$.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 21:37
S33	1307	S32 and S24	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 23:39
S34	590075	S21 same (annular\$3 ring circular)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 23:40
S35	23675	S34 and S22 and S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 23:40

EAST Search History

S36	338606	S21 with (annular\$3 ring circular)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 23:40
S37	10552	S36 and S22 and S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 23:41
S38	20248	S36 same S22	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 23:41
S39	2952	S38 and S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 23:42
S40	227	S39 and ("257"/\$.ccls. "438"/\$.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/21 23:42
S41	119	(power near module) with (heat near exchange\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 18:11
S42	0	S41 same (rubber with seal)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 18:11

EAST Search History

S43	264	(power near module) same (heat near exchange\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 18:11
S44	0	S43 same (rubber with seal)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 18:11
S45	1016	(power near module) and (heat near exchange\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 18:11
S46	10	S45 and (rubber with seal)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 18:12
S47	1059478	power and (semiconductor chip die ic (integrated near circuit\$2) dice)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 18:13
S48	406	(heat near exchange\$3) same (rubber with seal)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 18:25
S49	38	S48 and S47	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 18:13

EAST Search History

S50	3678	(cool\$3 (heat near (spread\$3 sink radiat\$3))) same (rubber with seal)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 17:09
S51	440	S50 and S47	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 18:26
S52	9	("20030114022" "4630096" "4663649" "4876588" "5338971" "6078491" "6084775" "6731011").PN. OR ("6849941"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/27 14:50
S53	15	("20020179287" "20030116312" "20040223303" "5367193" "5594623" "5658831" "5969949" "5981085" "6114048" "6245442" "6702007" "6847113" "6849941" "6898084" "6977814").PN. OR ("7219721"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/27 16:28
S54	5	"840303".ap.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/27 16:28
S55	119515	(cool\$3 (heat near (spread\$3 sink radiat\$3 exchang\$3))) same (elastin elastic\$4 rubber resilien\$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 17:33
S56	1059478	power and (semiconductor chip die ic (integrated near circuit\$2) dice)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 17:20
S57	12207	S55 and S56	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 17:20

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S58	2729458	(cool\$3 (heat near (spread\$3 sink radiat\$3 exchang\$3)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 17:31
S59	408385	(elastin elastic\$4 rubber resilien\$2) same seal\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 18:29
S60	10262	S56 and S58 and S59	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 17:34
S61	25471	S58 same S59	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 17:34
S62	2756	S61 and S56	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 18:28
S63	351	S62 and ("257"/\$.ccls. "361"/\$.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 17:40
S64	20	("2461087" "2825014" "3264531" "3373335" "3437887" "3443168" "3651383" "4099201" "4326238").PN. OR ("4538171").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/27 17:57

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S65	2405	S62 not S63	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 18:28
S66	277396	(elastin elastic\$4 rubber resilien\$2) with seal\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 18:29
S67	13859	S58 same S66	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 18:29
S68	1343	S67 and S56	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 18:30
S69	1144	S68 not S63	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 18:32
S70	1	2001-584287.NRAN.	DERWENT	OR	ON	2007/07/29 20:33
S71	1	2001-584287.NRAN.	DERWENT	OR	ON	2007/07/29 20:44
S72	4081	(257/712,718).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/29 20:44
S73	770	S72 and (rubber elastin elastic\$4 resilien\$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 20:45

EAST Search History

S74	89	S72 and ((rubber elastin elastic\$4 resilien\$2) same (annular\$2 ring o-ring (o near ring)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 20:45
S75	52	S72 and ((rubber elastin elastic\$4 resilien\$2) with (annular\$2 ring o-ring (o near ring)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 21:15
S76	12	("20030127714" "5619399" "592012 0" "6750551").PN. ("5413489" "6349032").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 21:30
S77	64	S75 S76	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 21:32
S78	36	S74 not S77	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:22
S79	100	S74 S77	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 21:39
S80	1	2005-420552.NRAN.	DERWENT	OR	ON	2007/07/29 22:19
S81	1059539	power and (semiconductor chip die ic (integrated near circuit\$2) dice)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:19

EAST Search History

S82	2729634	(cool\$3 (heat near (spread\$3 sink radiat\$3 exchang\$3)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:19
S83	408396	(elastin elastic\$4 rubber resilien\$2) same seal\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:19
S84	25471	S82 same S83	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:19
S85	2756	S84 and S81	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:19
S86	351	S85 and ("257"/\$.ccls. "361"/\$.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:19
S87	277407	(elastin elastic\$4 rubber resilien\$2) with seal\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:19
S88	13859	S82 same S87	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:19

EAST Search History

S89	1343	S88 and S81	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:19
S90	1144	S89 not S86	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:19
S91	24	S79 S90	DERWENT	OR	ON	2007/07/29 22:21
S92	1244	S79 S90	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:21
S93	679	S73 not S92	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 23:03
S94	146	S93 and (encapsulat\$3 encapsulant)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 22:22
S95	38	("4531146" "4612601" "4612978" "4644385" "4878108" "5089936" "5175613" "5184211" "5345107").PN. OR ("5886408"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/29 23:01
S96	1391	S92 S94 S95	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/29 23:03
S97	532	S93 not S96	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 23:03